

Si552 **REVISION D**

DUAL FREQUENCY VOLTAGE-CONTROLLED CRYSTAL OSCILLATOR (VCXO) 10 MHz TO 1.4 GHz

Internal fixed crystal frequency

 Available CMOS, LVPECL, LVDS, and CML outputs

Industry-standard 5 x 7 mm

package and pinout

Pb-free/RoHS-compliant

Low-jitter clock generation

Clock and data recovery

Optical modules

aging

ensures high reliability and low

Features

- Available with any-rate output frequencies from 10–945 MHz and selected frequencies to 1.4 GHz
- Two selectable output frequencies
- 3rd generation DSPLL[®] with superior jitter performance
- 3x better frequency stability than SAW-based oscillators

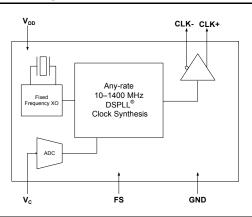
Applications

- SONET/SDH
- **xDSL**
- 10 GbE LAN/WAN

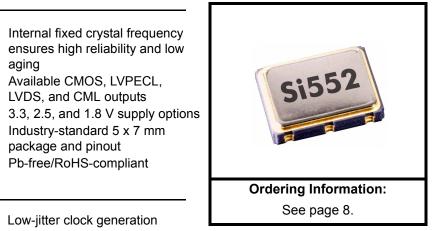
Description

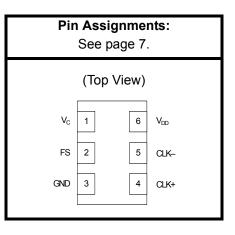
The Si552 dual-frequency VCXO utilizes Silicon Laboratories' advanced DSPLL[®] circuitry to provide a very low jitter clock for all output frequencies. The Si552 is available with anv-rate output frequency from 10 to 945 MHz and selected frequencies to 1400 MHz. Unlike traditional VCXOs, where a different crystal is required for each output frequency, the Si552 uses one fixed crystal frequency to provide a wide range of output frequencies. This IC-based approach allows the crystal resonator to provide exceptional frequency stability and reliability. In addition, DSPLL clock synthesis provides superior supply noise rejection, simplifying the task of generating low-jitter clocks in noisy environments typically found in communication systems. The Si552 IC-based VCXO is factory-configurable for a wide variety of user specifications including frequency, supply voltage, output format, tuning slope, and temperature stability. Specific configurations are factory programmed at time of shipment, thereby eliminating the long lead times associated with custom oscillators.

Functional Block Diagram



Rev. 0.6 6/07





1. Electrical Specifications

Table 1. Recommended Operating Conditions

Parameter	Symbol	Test Condition	Min	Тур	Мах	Units
Supply Voltage ¹	V _{DD}	3.3 V option	2.97	3.3	3.63	
		2.5 V option	2.25	2.5	2.75	V
		1.8 V option	1.71	1.8	1.89	
Supply Current	I _{DD}	Output enabled				
		LVPECL	_	120	130	
		CML	_	108	117	
		LVDS	_	99	108	mA
		CMOS	_	90	98	
		Tristate mode	_	60	75	
Frequency Select (FS) ²		V _{IH}	0.75 x V _{DD}	—	—	V
		V _{IL}	—	_	0.5	
Operating Temperature Range	T _A		-40	_	85	°C

1. Selectable parameter specified by part number. See Section 3. "Ordering Information" on page 8 for further details.

2. FS pin includes a 17 k Ω resistor to VDD.

Table 2. V_C Control Voltage Input

Parameter	Symbol	Test Condition	Min	Тур	Max	Units
Control Voltage Tuning Slope ^{1,2,3}	K _V	10 to 90% of V _{DD}	—	33	_	ppm/V
				45		
				90		
				135		
				180		
				356		
Control Voltage Linearity ⁴	L _{VC}	BSL	-5	±1	+5	%
		Incremental	-10	±5	+10	/0
Modulation Bandwidth	BW		9.3	10.0	10.7	kHz
V _C Input Impedance	Z _{VC}		500			kΩ
Nominal Control Voltage	V _{CNOM}	@ f _O	—	V _{DD} /2		V
Control Voltage Tuning Range	V _C		0		V _{DD}	V

Notes:

2

1. Positive slope; selectable option by part number. See Section 3. "Ordering Information" on page 8.

For best jitter and phase noise performance, always choose the smallest K_V that meets the application's minimum APR requirements. See "AN266: VCXO Tuning Slope (K_V), Stability, and Absolute Pull Range (APR)" for more information.

3. K_V variation is ±10% of typical values.

4. BSL determined from deviation from best straight line fit with V_C ranging from 10 to 90% of V_{DD} . Incremental slope determined with V_C ranging from 10 to 90% of V_{DD} .



Table 3. CLK± Output Frequency Characteristics

Parameter	Symbol	Test Condition	Min	Тур	Мах	Units
Nominal Frequency ^{1,2,3}	f _O	LVDS/CML/LVPECL	10	_	945	MHz
		CMOS	10		160	
Temperature Stability ^{1,4}		T _A = -40 to +85 °C	-20	_	+20	
			-50	—	+50	ppm
			-100	—	+100	
Absolute Pull Range ^{1,4}	APR		±25	_	±375	ppm
Aging		Frequency drift over first year.		_	±3	nnm
		Frequency drift over 15 year life.		_	±10	- ppm
Power up Time ⁵	t _{osc}				10	ms
Settling Time After FS Change	t _{FRQ}		_	_	10	ms

Notes:

1. See Section 3. "Ordering Information" on page 8 for further details.

- 2. Specified at time of order by part number. Also available in frequencies from 970 to 1134 MHz and 1213 to 1417 MHz.
- **3.** Nominal output frequency set by $V_{CNOM} = V_{DD}/2$.
- 4. Selectable parameter specified by part number.
- **5.** Time from power up or tristate mode to f_O (to within ±1 ppm of f_O).

Table 4. CLK± Output Levels and Symmetry

Symbol	Test Condition	Min	Тур	Max	Units
V _O	mid-level	V _{DD} – 1.42	_	V _{DD} – 1.25	V
V _{OD}	swing (diff)	1.1		1.9	V _{PP}
V _{SE}	swing (single-ended)	0.55		0.95	V _{PP}
V _O	mid-level	1.125	1.20	1.275	V
V _{OD}	swing (diff)	0.5	0.7	0.9	V_{PP}
V _O	mid-level	—	$V_{DD} - 0.75$	—	V
V _{OD}	swing (diff)	0.70	0.95	1.20	V_{PP}
V _{OH}	I _{OH} = 32 mA	0.8 x V _{DD}	_	V _{DD}	V
V _{OL}	I _{OL} = 32 mA	—		0.4	v
t _{R,} t _F	LVPECL/LVDS/CML		_	350	ps
	CMOS with C _L = 15 pF	—	1	—	ns
SYM	LVPECL: V _{DD} – 1.3 V (diff) LVDS: 1.25 V (diff) CMOS: V _{DD} /2	45		55	%
	V _O V _{OD} V _{SE} V _O V _{OD} V _{OD} V _{OD} V _{OH} V _{OL}	$\begin{tabular}{ c c c c } \hline V_O & mid-level \\ \hline V_{OD} & swing (diff) \\ \hline V_{SE} & swing (single-ended) \\ \hline V_O & mid-level \\ \hline V_{OD} & swing (diff) \\ \hline V_O & mid-level \\ \hline V_{OD} & swing (diff) \\ \hline V_{OH} & I_{OH} = 32 mA \\ \hline V_{OL} & I_{OL} = 32 mA \\ \hline V_{OL} & I_{OL} = 32 mA \\ \hline t_{R}, t_F & LVPECL/LVDS/CML \\ \hline CMOS with C_L = 15 pF \\ \hline SYM & LVPECL: & V_{DD} - 1.3 V (diff) \\ LVDS: & 1.25 V (diff) \\ \hline \end{array}$	$\begin{tabular}{ c c c c c c } \hline V_O & mid-level & V_{DD}-1.42 \\ \hline V_{OD} & swing (diff) & 1.1 \\ \hline V_{SE} & swing (single-ended) & 0.55 \\ \hline V_O & mid-level & 1.125 \\ \hline V_{OD} & swing (diff) & 0.5 \\ \hline V_O & mid-level & \\ \hline V_{OD} & swing (diff) & 0.70 \\ \hline V_{OH} & I_{OH} = 32 \text{mA} & 0.8 \text{x} \text{V}_{DD} \\ \hline V_{OL} & I_{OL} = 32 \text{mA} & \\ \hline t_{R,} t_F & LVPECL/LVDS/CML & \\ \hline CMOS with C_L = 15 \text{pF} & \\ \hline SYM & LVPECL: V_{DD} - 1.3 \text{V} (diff) \\ LVDS: & 1.25 \text{V} (diff) & 45 \\ \hline \end{tabular}$	$\begin{tabular}{ c c c c c c c } \hline V_O & mid-level & V_{DD}-1.42 & \\ \hline V_{OD} & swing (diff) & 1.1 & \\ \hline V_{SE} & swing (single-ended) & 0.55 & \\ \hline V_O & mid-level & 1.125 & 1.20 \\ \hline V_{OD} & swing (diff) & 0.5 & 0.7 \\ \hline V_O & mid-level & & V_{DD}-0.75 \\ \hline V_{OD} & swing (diff) & 0.70 & 0.95 \\ \hline V_{OD} & swing (diff) & 0.70 & 0.95 \\ \hline V_{OL} & I_{OL} = 32 \text{ mA} & 0.8 \text{ x } V_{DD} & \\ \hline V_{OL} & I_{OL} = 32 \text{ mA} & & \\ \hline t_{R,} t_F & LVPECL/LVDS/CML & & \\ \hline CMOS \text{ with } C_L = 15 \text{ pF} & & 1 \\ \hline SYM & LVPECL: & V_{DD} - 1.3 \text{ V } (diff) \\ LVDS: & 1.25 \text{ V } (diff) & 45 & \\ \hline \end{tabular}$	$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$

1. 50 Ω to V_{DD} – 2.0 V. **2.** R_{term} = 100 Ω (differential).

3. $C_L = 15 \, \text{pF}$



Table 5. CLK± Output Phase Jitter

Parameter	Symbol	Test Condition	Min	Тур	Мах	Units
Phase Jitter (RMS) ^{1,2,3}	фJ	Kv = 33 ppm/V				ps
for F _{OUT} ≥ 500 MHz		12 kHz to 20 MHz (OC-48)	_	0.26	—	-
		50 kHz to 80 MHz (OC-192)	—	0.26	—	
		Kv = 45 ppm/V				
		12 kHz to 20 MHz (OC-48)	—	0.27	—	
		50 kHz to 80 MHz (OC-192)	—	0.26	—	
		Kv = 90 ppm/V				
		12 kHz to 20 MHz (OC-48)	—	0.32	—	
		50 kHz to 80 MHz (OC-192)	—	0.26	—	
		Kv = 135 ppm/V				
		12 kHz to 20 MHz (OC-48)	—	0.40	—	
		50 kHz to 80 MHz (OC-192)	—	0.27	—	
		Kv = 180 ppm/V				
		12 kHz to 20 MHz (OC-48)	—	0.49	—	
		50 kHz to 80 MHz (OC-192)	—	0.28	—	
		Kv = 356 ppm/V				1
		12 kHz to 20 MHz (OC-48)	—	0.87	—	
		50 kHz to 80 MHz (OC-192)	—	0.33	—	

Notes:

1. Differential Modes: LVPECL/LVDS/CML. Refer to AN255, AN256, and AN266 for further information.

For best jitter and phase noise performance, always choose the smallest K_V that meets the application's minimum APR requirements. See "AN266: VCXO Tuning Slope (K_V), Stability, and Absolute Pull Range (APR)" for more information.
 See "AN255: Replacing 622 MHz VCSO devices with the Si550 VCXO" for comparison highlighting power supply

rejection (PSR) advantage of Si55x versus SAW-based solutions.



Table 5. CLK± Output Phase Jitter (Continued)

Parameter	Symbol	Test Condition	Min	Тур	Max	Units
Phase Jitter (RMS) ^{1,2,3}	фj	Kv = 33 ppm/V				ps
for F _{OUT} of 125 to 500 MHz		12 kHz to 20 MHz (OC-48)	_	0.37	—	
		50 kHz to 80 MHz (OC-192)	_	0.33	—	
		Kv = 45 ppm/V				
		12 kHz to 20 MHz (OC-48)	_	0.37	_	
		50 kHz to 80 MHz (OC-192)	—	0.33	—	
		Kv = 90 ppm/V				
		12 kHz to 20 MHz (OC-48)	_	0.43	_	
		50 kHz to 80 MHz (OC-192)	—	0.34	—	
		Kv = 135 ppm/V				
		12 kHz to 20 MHz (OC-48)	—	0.50	—	
		50 kHz to 80 MHz (OC-192)	—	0.34	—	
		Kv = 180 ppm/V				
		12 kHz to 20 MHz (OC-48)	_	0.59	_	
		50 kHz to 80 MHz (OC-192)	—	0.35	—	
		Kv = 356 ppm/V				1
		12 kHz to 20 MHz (OC-48)	_	1.00		
		50 kHz to 80 MHz (OC-192)	_	0.39	—	

Notes:

1. Differential Modes: LVPECL/LVDS/CML. Refer to AN255, AN256, and AN266 for further information.

For best jitter and phase noise performance, always choose the smallest K_V that meets the application's minimum APR requirements. See "AN266: VCXO Tuning Slope (K_V), Stability, and Absolute Pull Range (APR)" for more information.

3. See "AN255: Replacing 622 MHz VCSO devices with the Si550 VCXO" for comparison highlighting power supply rejection (PSR) advantage of Si55x versus SAW-based solutions.

Table 6. CLK± Output Period Jitter

Parameter	Symbol	Test Condition	Min	Тур	Max	Units	
Period Jitter*	J _{PER}	RMS	_	2	—	ps	
		Peak-to-Peak		14	—		
*Note: Any output mode, including CMOS, LVPECL, LVDS, CML. N = 1000 cycles. Refer to AN279 for further information.							



Offset Frequency	74.25 MHz 90 ppm/V	491.52 MHz 45 ppm/V	622.08 MHz 135 ppm/V	Units
	LVPECL	LVPECL	LVPECL	
100 Hz	-87	-75	-65	
1 kHz	-114	-100	-90	
10 kHz	-132	-116	-109	
100 kHz	-142	-124	-121	dBc/Hz
1 MHz	-148	-135	-134	
10 MHz	-150	-146	-146	
100 MHz	n/a	-147	-147	

Table 7. CLK± Output Phase Noise (Typical)

Table 8. Absolute Maximum Ratings¹

Parameter	Symbol	Rating	Units
Maximum Operating Temperature	T _{AMAX}	85	°C
Supply Voltage	V _{DD}	-0.5 to +3.8	Volts
Input Voltage (any input pin)	VI	-0.5 to V _{DD} + 0.3	Volts
Storage Temperature	Τ _S	-55 to +125	°C
ESD Sensitivity (HBM, per JESD22-A114)	ESD	2500	Volts
Soldering Temperature (Pb-free profile) ²	T _{PEAK}	260	°C
Soldering Temperature Time @ T _{PEAK} (Pb-free profile) ²	t _P	20–40	seconds
		1	

Notes:

1. Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Functional operation or specification compliance is not implied at these conditions. Exposure to maximum rating conditions for extended periods may affect device reliability.

2. The device is compliant with JEDEC J-STD-020C. Refer to Si5xx Packaging FAQ available for download from www.silabs.com/VCXO for further information, including soldering profiles.

Table 9. Environmental Compliance

The Si552 meets the following qualification test requirements.

Parameter	Conditions/Test Method
Mechanical Shock	MIL-STD-883F, Method 2002.3 B
Mechanical Vibration	MIL-STD-883F, Method 2007.3 A
Solderability	MIL-STD-883F, Method 203.8
Gross & Fine Leak	MIL-STD-883F, Method 1014.7
Resistance to Solvents	MIL-STD-883F, Method 2016



2. Pin Descriptions

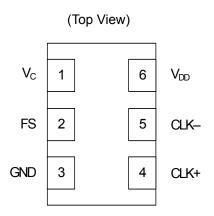


Table 10. Si552 Pin Descriptions

Pin	Name	Туре	Function				
1	V _C	Analog Input	Control Voltage				
2	FS*	Input	Frequency Select: 0 = first frequency selected 1 = second frequency selected				
3	GND	Ground	Electrical and Case Ground				
4	CLK+	Output	Oscillator Output				
5	CLK– (N/A for CMOS)	Output	Complementary Output (N/C for CMOS)				
6	V _{DD}	Power	Power Supply Voltage				
	*Note: FS includes a 17 kΩ pullup resistor to V _{DD} . See Section 3. "Ordering Information" on page 8 for details on frequency select and OE polarity ordering options.						



3. Ordering Information

The Si552 supports a variety of options including frequency, temperature stability, tuning slope, output format, and V_{DD} . Specific device configurations are programmed into the Si552 at time of shipment. Configurations are specified using the Part Number Configuration chart shown below. Silicon Labs provides a web browser-based part number configuration utility to simplify this process. Refer to www.silabs.com/VCXOPartNumber to access this tool and for further ordering instructions. The Si552 VCXO series is supplied in an industry-standard, RoHS-compliant, lead-free, 6-pad, 5 x 7 mm package. Tape and reel packaging is an ordering option.

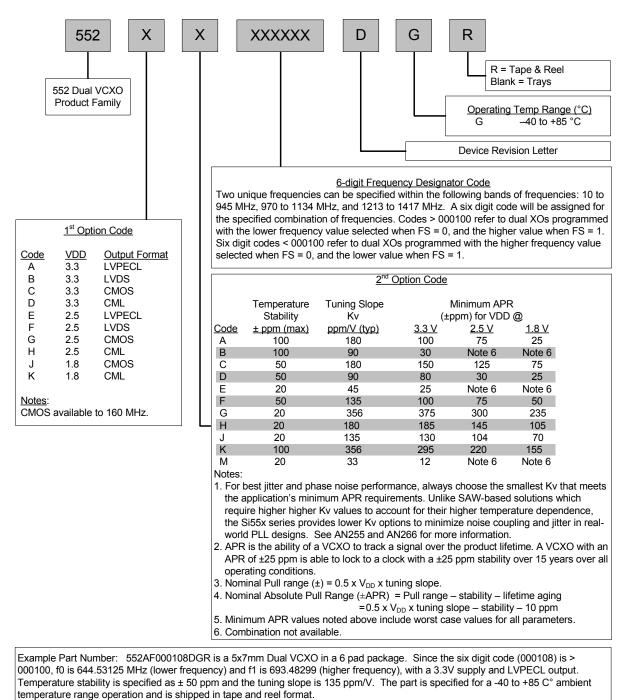


Figure 1. Part Number Convention



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4. Si55x Mark Specification

Figure 2 illustrates the mark specification for the Si552. Table 11 lists the line information.



Figure 2. Mark Specification

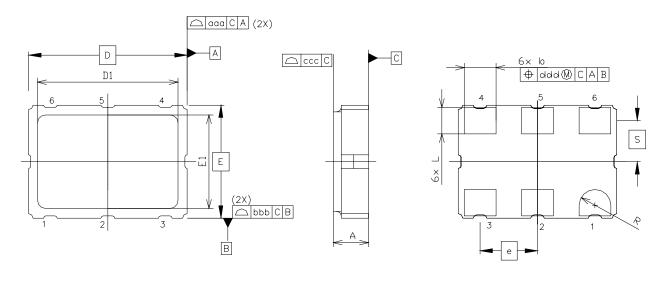
Table 11. Si55x Top Mark Description

Line	Position	Description				
1	1–10	"SiLabs"+ Part Family Number, 5xx (First 3 characters in part number)				
2	1–10	Si550: Option1+Option2+Freq(7)+Temp Si552, Si554, Si550 w/ 8-digit resolution: Option1+Option2+ConfigNum(6)+Ter				
3	Trace Code					
	Position 1	Pin 1 orientation mark (dot)				
	Position 2	Product Revision (D)				
	Position 3–6	Tiny Trace Code (4 alphanumeric characters per assembly release instructions)				
	Position 7	Year (least significant year digit), to be assigned by assembly site (ex: 2007 = 7)				
	Position 8–9 Calendar Work Week number (1–53), to be assigned by assembly site					
	Position 10	"+" to indicate Pb-Free and RoHS-compliant				



5. Outline Diagram and Suggested Pad Layout

Figure 3 illustrates the package details for the Si552. Table 12 lists the values for the dimensions shown in the illustration.



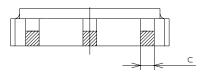


Figure 3. Si552 Outline Diagram

Dimension	Min	Nom	Max
А	1.45	1.65	1.85
b	1.2	1.4	1.6
С	0.60 TYP		
D	7.00 BSC		
D1	6.10	6.2	6.30
е	2.54 BSC		
E	5.00 BSC		
E1	4.30	4.40	4.50
L	1.07	1.27	1.47
S	1.815 BSC		
R	0.7 REF		
aaa	—		0.15
bbb	—	—	0.15
CCC	—	—	0.10
ddd	—	—	0.10

Table 12. Package Diagram Dimensions (mm)



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6. 6-Pin PCB Land Pattern

Figure 4 illustrates the 6-pin PCB land pattern for the Si552. Table 13 lists the values for the dimensions shown in the illustration.

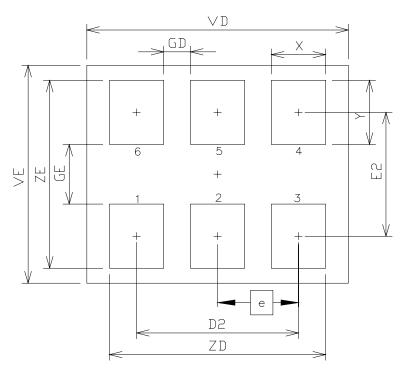


Figure 4. Si552 PCB Land Pattern

Dimension	Min	Max	
D2	5.08 REF		
е	2.54 BSC		
E2	4.15 REF		
GD	0.84		
GE	2.00		
VD	8.20 REF		
VE	7.30 REF		
Х	1.70 TYP		
Y	2.15	REF	
ZD	—	6.78	
ZE		6.30	

Table 13. PCB Land Pattern Dimensions (mm)

1. Dimensioning and tolerancing per the ANSI Y14.5M-1994 specification.

2. Land pattern design based on IPC-7351 guidelines.

3. All dimensions shown are at maximum material condition (MMC).

4. Controlling dimension is in millimeters (mm).



DOCUMENT CHANGE LIST

Revision 0.3 to Revision 0.4

- Updated Table 1, "Recommended Operating Conditions," on page 2.
 - Added maximum supply current specifications.
 - Specified relationship between temperature at startup and operation temperature.

Revision 0.4 to Revision 0.5

 Updated Note 3 in Table 1, "Recommended Operating Conditions," on page 2.

Revision 0.5 to Revision 0.6

- Updated Table 1, "Recommended Operating Conditions," on page 2.
 - Device maintains stable operation over -40 to +85 °C operating temperature range.
 - Supply current specifications updated for revision D.
- Updated Table 4, "CLK± Output Levels and Symmetry," on page 3.
 - Updated LVDS differential peak-peak swing specifications.
- Updated Table 5, "CLK± Output Phase Jitter," on page 4.
- Updated Table 6, "CLK± Output Period Jitter," on page 5.
 - Revised period jitter specifications.
- Updated Table 8, "Absolute Maximum Ratings¹," on page 6 to reflect the soldering temperature time at 260 °C is 20–40 sec per JEDEC J-STD-020C.
- Updated 3. "Ordering Information" on page 8.
 Changed ordering instructions to revision D.
- Added 4. "Si55x Mark Specification" on page 9.



NOTES:

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